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What is claimed is:

1. A mask for screen printing including a positive pattern section and a negative pattern section with a mask material formed on said negative pattern section, for transferring a printing ink material to a substrate via openings of a mesh disposed at said positive pattern section, wherein:

said negative pattern section of said mesh selectively has a mesh opening ratio which is smaller than an opening ratio of said positive pattern section.

- 2. The mask according to claim 1, wherein a width of a gap, which is formed on said substrate by said negative pattern section, is not more than 40  $\mu m$ .
- 3. The mask according to claim 1, wherein a plating layer is formed on said mesh of said negative pattern section.
- 4. The mask according to claim 3, wherein said plating layer has a thickness of 1 to 20  $\mu m.$
- 5. A mask for screen printing including a positive pattern section and a negative pattern section, for transferring a printing ink material to a substrate via openings of a mesh disposed at said positive pattern

section, wherein:

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said negative pattern section has a mesh opening ratio of zero.

- The mask according to claim 5, wherein a plating layer is formed on said mesh of said negative pattern section.
- 7. A method for producing a mask for screen printing including a positive pattern section and a negative pattern section with a mask material formed on said negative pattern section, for transferring a printing ink material to a substrate via openings of a mesh disposed at said positive pattern section, wherein:

a plating treatment is selectively applied beforehand to said mesh of said negative pattern section so that said negative pattern section has a mesh opening ratio which is smaller than an opening ratio of said positive pattern section.

- 8. The method for producing said mask according to claim 7, wherein at least a surface of both surfaces of a screen, on which a squeegee makes sliding movement, is polished after said plating treatment to give a flatness.
- 9. The method for producing said mask according to claim 7, wherein a plating mask material is formed before

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said plating treatment on a surface of both surfaces of a screen, on which a squeegee makes sliding movement so that said plating layer is not formed on said surface.

- 10. The method for producing said mask according to claim 7, wherein said plating layer is composed of a material which has a hardness lower than that of said screen so that said plating layer is easily polished.
- 11. A circuit board comprising a pattern formed by screen printing, said pattern including at least one of a passive device such as a capacitor element and/or an active device such as an electromechanical conversion element, wherein:
  - a gap between said pattern is not more than 40  $\mu\text{m}\text{.}$
- 12. The circuit board according to claim 11, wherein: if it is assumed that a plurality of patterns are formed in an aligned manner;
- a difference between an average thickness of a pattern corresponding to a pattern assumed to be formed by an odd-numbered operation and an average thickness of a pattern corresponding to a pattern assumed to be formed by an even-numbered operation is not more than 5 % of an overall average thickness.
  - 13. The circuit board according to claim 11, wherein:

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said screen printing is performed by using a mask including a positive pattern section and a negative pattern section with a mask material formed on said negative pattern section, for transferring a printing ink material to a substrate via openings of a mesh disposed at said positive pattern section, and wherein:

said negative pattern section of said mesh selectively has a mesh opening ratio which is smaller than an opening ratio of said positive pattern section.

- 14. The circuit board according to claim 13, wherein a plating layer is formed on said mesh of said negative pattern section of said mask.
- 15. The circuit board according to claim 14, wherein said plating layer has a thickness of 1 to 20  $\mu m\,.$
- 16. The circuit board according to claim 11, wherein said pattern is formed by one time of screen printing.